

IN THE SPECIFICATION:

Please replace the paragraph [001] with the following rewritten paragraph:

--This application claims priority under 35 USC § 120 of provisional application Serial No. 10/252,217, filed 9/23/2002. The present application is a divisional of the above identified application. The invention relates to an IC package mold lock and methods for making the same. More particularly, the invention relates to leadframe-to-plastic lock structures and methods for use in IC packages. —